Components marked "ON" should not be populated.

Assembly Variant: 001

PCB VIEWED FROM TOP SIDE  |  BOARD #: TIDH-DD08  |  REVIS: 1.0  |  SUN REVIS Not In VersionControl
---|---|---|---
TID: TIDH0008

PLOT NAME: Top Assembly Drawing  |  GENERATED: 2-6-2017 11:38:22 AM  |  TEXAS INSTRUMENTS
COMPONENTS MARKED "OMP" SHOULD NOT BE POPULATED.
ASSEMBLY VARIANTS DO!

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD 4: TIDH-0508</th>
<th>REA 1.0</th>
<th>SUI REH: Net In VersionControl</th>
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<tr>
<td>TJD 4: TJD00108</td>
<td></td>
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<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED 1 2/6/2007 1:11BZ4 A1</td>
<td>TEXAS INSTRUMEN</td>
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